新應材股份有限公司
Advanced Echem Materials Company Ltd.

Stock code：4749

Investor Conference

May, 2026

Safe Harbor Notice

- AEMC’ s statements of its current expectations are forward-looking statements subject to significant risks and uncertainties and actual results may differ materially from those contained in the forward-looking statements.

- AEMC makes no representation or warranty regarding such forward-looking statements. Except as required by law, AEMC undertakes no obligation to update any forward-looking statements, whether as a result of new information, future events, or otherwise.

Agenda

- Company Overview
- Main Products and Markets
- Product Roadmap
- Financial Highlights
- ESG Performance
- Appendix

Our Mission and Vision

Mission

Establish upstream and downstream supply chains.

Our mission is to establish Taiwan's independent technology in specialty chemicals for advanced semiconductor processes and through collaboration, enhance the global competitiveness of the local specialized materials industry, both upstream and downstream.

Vision

Expand the variety of lithography materials and increase market share.

Our vision is to enhance Synthesis, Purification, Formulation, and process technologies to meet customer needs, assist in yield improvement deliver exceptional added value, and become an innovative specialty chemical company with global competitiveness.

Awards

- **TSMC Excellent Performance Award, 2022**
  Excellent Material Development and Production Support in Lithography Materials.
- **National Industrial Innovation Award, 2023**

About AEMC

Paid-in Capital : NT$926M / US$30.8M
Number of Employees : 465 (2026.04)
R&D Personnel : 138 (2026.04)

Locations

Taoyuan Factory : HQ with R&D Center, Display Photo Resists, Optical Component Materials
Tainan Factory : Semiconductor Specialty Chemicals
Kaohsiung Factory P1, P2 (Under Qualification) : Semiconductor Specialty Chemicals

Main Products

- Specialty Materials for Semiconductors
  - Advanced Process Materials
  - Advanced Packaging Materials
  - Optical Component Materials
- Specialty Materials for Displays
  - Display Photoresist

Invested Companies

- AEMC JAPAN (100%)
- AEMC USA (100%)
- SCIWIN Laboratories (70%)
- Oleader Technologies (40%+Preferred shares 13.34%) Equity investment
- e-Ray Technology (26.28 %) Equity investment
- Advanced Pao Trusval Technology (26.87 %) Equity investment
- Full Chain Materials (in progress) New Investment

About AEMC

2003	Photoresist for Display
2014	Materials for Semiconductor Optical Components
2018	Materials for Advanced Semiconductor Processes
2025	Photoresist for Advanced Semiconductor Processes
2026	Materials for Advanced Packaging

Main Products

Semiconductor Specialty Chemicals

-Advanced Lithography Process

- Rinse
- EBR
- BARC
- Cleaner

-Advanced Packaging Material

-Optical Component

- Image Sensor Material
- Micro-Optical Component Material

Display Specialty Chemicals

-Display Photoresist

R&D and Production Sites

Sample Shipping

R&D Lab

Trial Production

SVM
Small Volume Manufacturing

Mass Production

HVM
High Volume Manufacturing

New Factory in Taoyuan (Longtan Science Park)

R&D Center, Semiconductor Specialty Materials

Scheduled for Completion in 2028

Taoyuan Factory

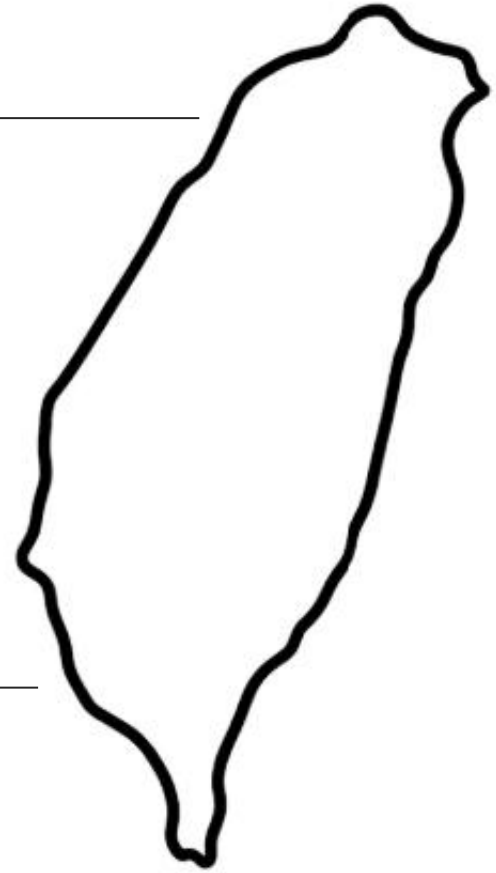
Display Photoresist
Optical Component Materials

Tainan Factory

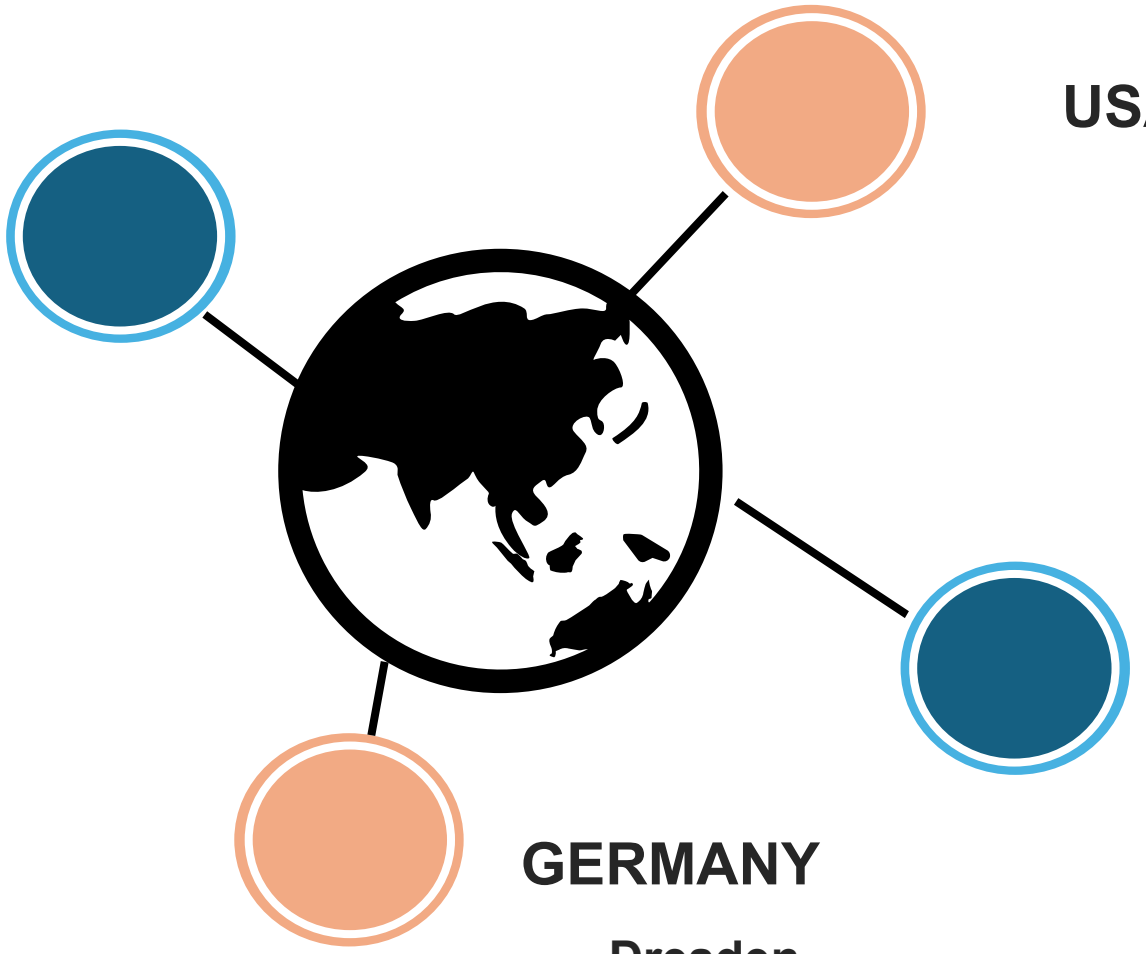
Semiconductor
Specialty Chemicals

Kaohsiung Factory

Semiconductor Specialty Chemicals



Major Customer's Advanced Process Capacity Roadmap (2025~)



TAIWAN

Hsinchu
4 Phases

Taichung
4 Phases

Tainan
9 Phases

Kaohsiung
6 Phases

USA

Arizona
4/3/2nm
8+ Phases

JAPAN

Kumamoto
28/22/16/12/ 3nm
2 Phases

GERMANY

Dresden
28~12nm
1 fab

Source: Economic Daily News, Digitimes, and other media reports.

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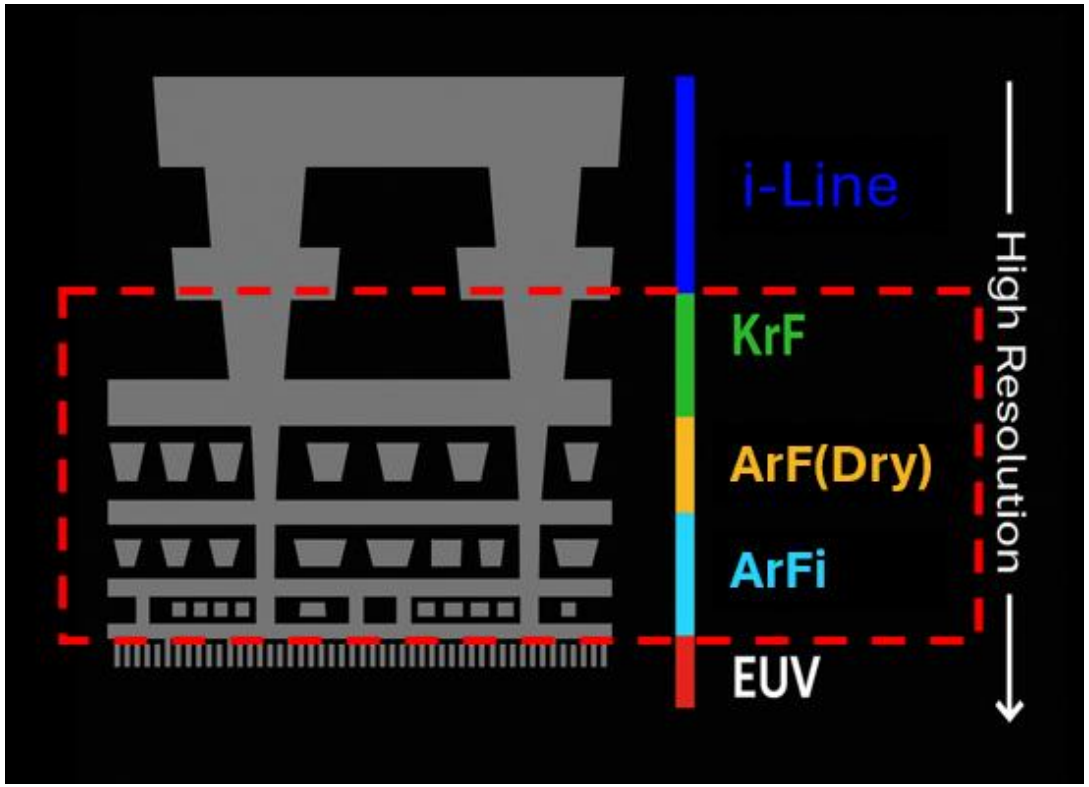
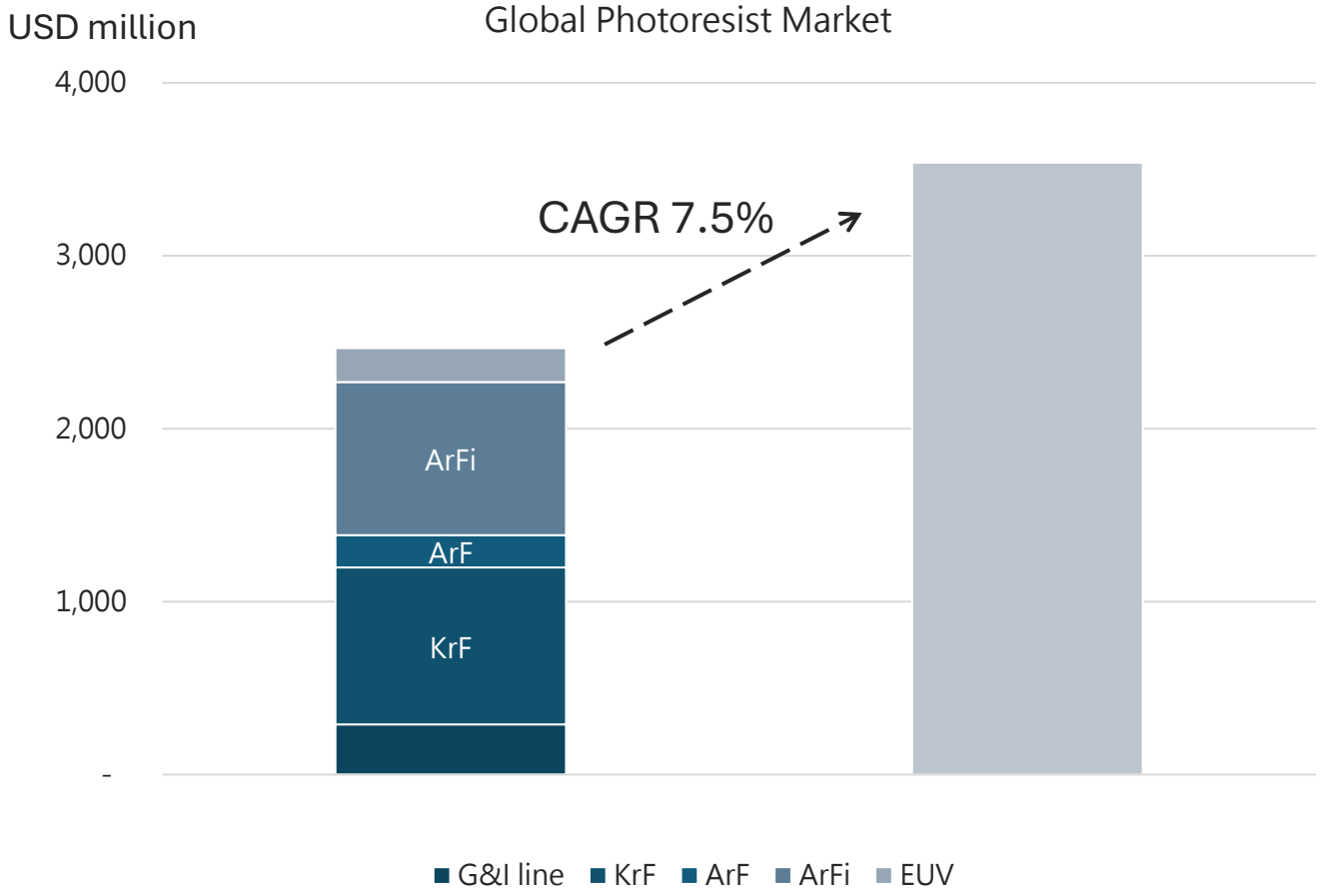
R&D Roadmap

Application Field	Mass Production	Verification	Developing
Advanced Microlithography Materials	• Rinse Material (表面改質劑) • BARC (底部抗反射層) • EBR (洗邊劑) • Cleaner (清洗劑)	• Rinse Material for next node • BARC for next node • EBR for next node • Cleaner for next node • DUV Photoresist (KrF)	• Bottom Layer for next node • Advanced BARC • Protection Layer • DUV Photoresist (ArF)
Advanced Packaging Materials	• Temporary Protection Layer • Plasma Dicing Glue	• Protection Layer for SoIC • KrF BARC • Cleaner • Protection Glue for CPO • Leveling Layer	• High AR Photoresist • Packaging Glue • Photoresist for Fine pitch QFN
Optical Element Materials	• Photoresists (光阻劑) • Flat Layer (平坦層) • Color Filter Layer (濾光層) • Light-cut Layer (遮光層) • Lift-off Layer(離型層)	• DUV Photoresist (ArF) • Stripper • Liff-off Layer for next node • ArF BARC • Adhesion Layer	• Leveling Layer • Microlens Materials

Photoresist Market





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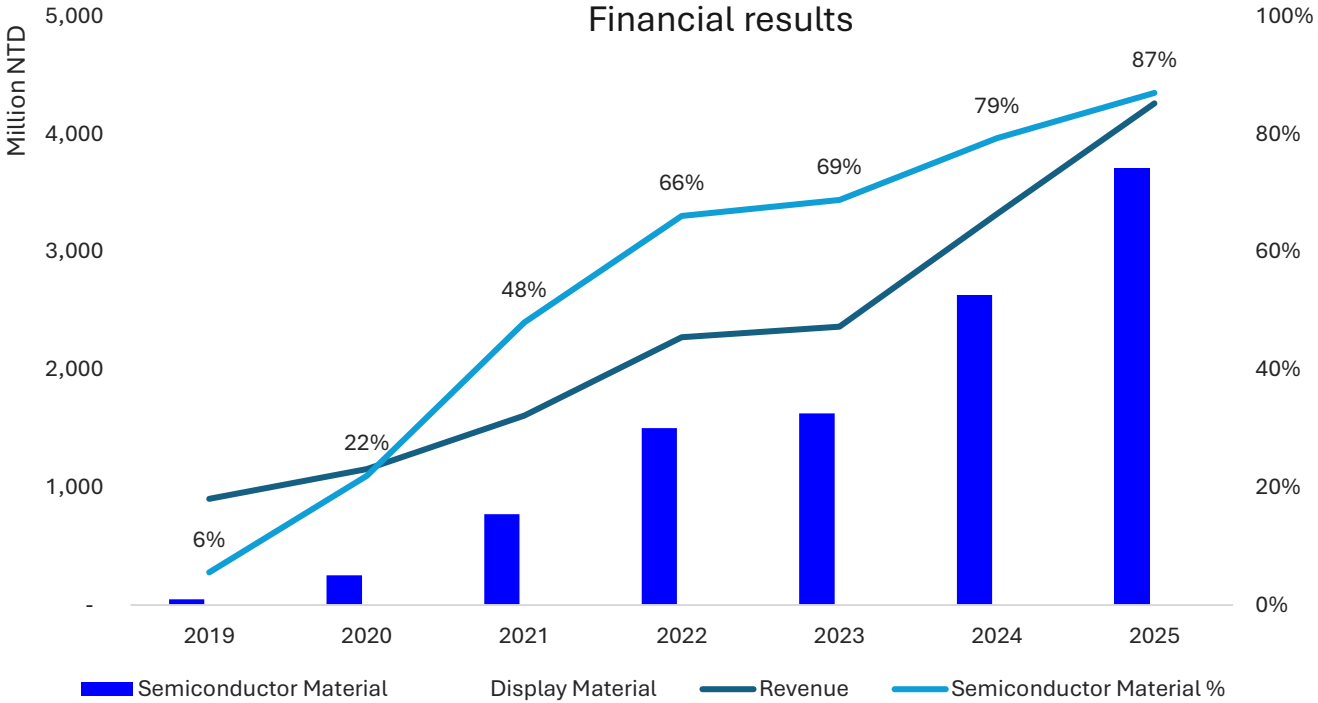
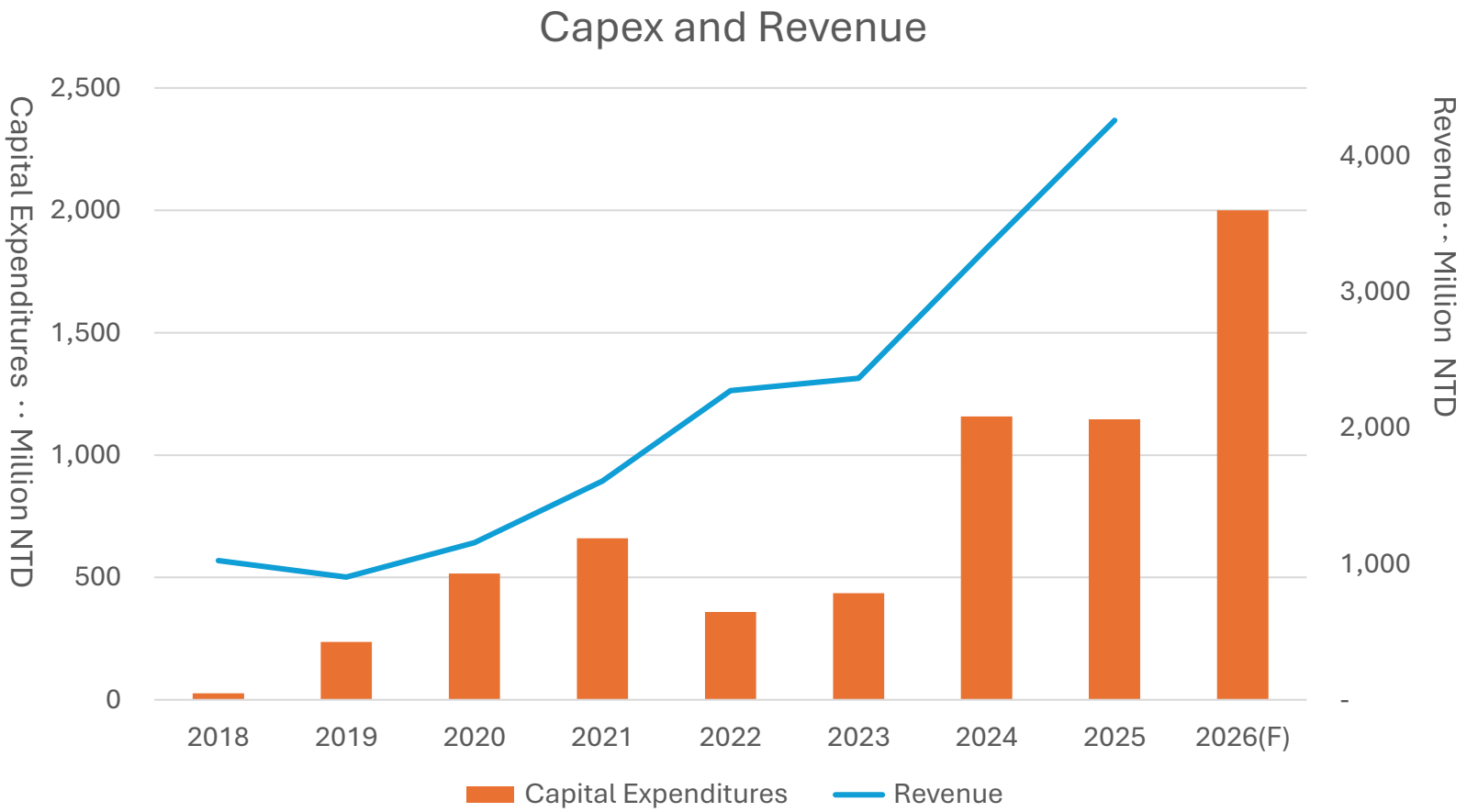
Financial Highlights



Year	2021	2022	2023	2024	2025	1Q2026
Revenue	1,609	2,274	2,364	3,322	4,262	1,246
Semiconductor Material	773	1,503	1,627	2,634	3,708	1,108
Display Material	836	771	737	688	554	138
Gross Profit	422	723	694	1,204	1,835	566
Gross Margin	26.2%	31.8%	29.4%	36.3%	43.1%	45.4%
Operating Income	53	295	225	587	1,061	337
Net Income Attributable to the Parent Company	122	404	318	698	1,044	340
EPS (NT$)	1.62	5.01	3.91	8.50	11.33	3.66

Capital Expenditures

Since 2018, AEMC has invested over NTD 4 billion in capital expenditures to support its transition into semiconductor materials development by the end of 2025.

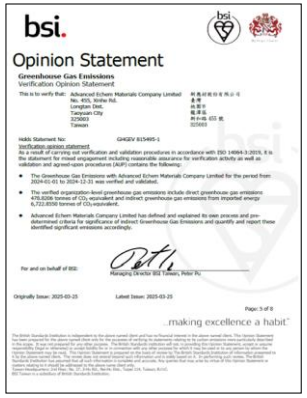


ESG Performance

Social Engagement

Integrating corporate initiatives with employee engagement to continuously enhance actions in public welfare and environmental sustainability.

Energy Efficiency and Carbon Reduction



Completed greenhouse gas inventory ahead of regulatory schedule and obtained a statement from a third-party verification body in 2024&2025.

Awarded a certificate of appreciation by a major wafer foundry customer for the 'Supplier Energy Saving and Carbon Reduction Guidance Program

Talent Sustainability

Established the 'AEMC Scholarship'

Founded the 'New Immigrant Children Scholarship'

Actively participated in 'Industry-Academia Cooperation

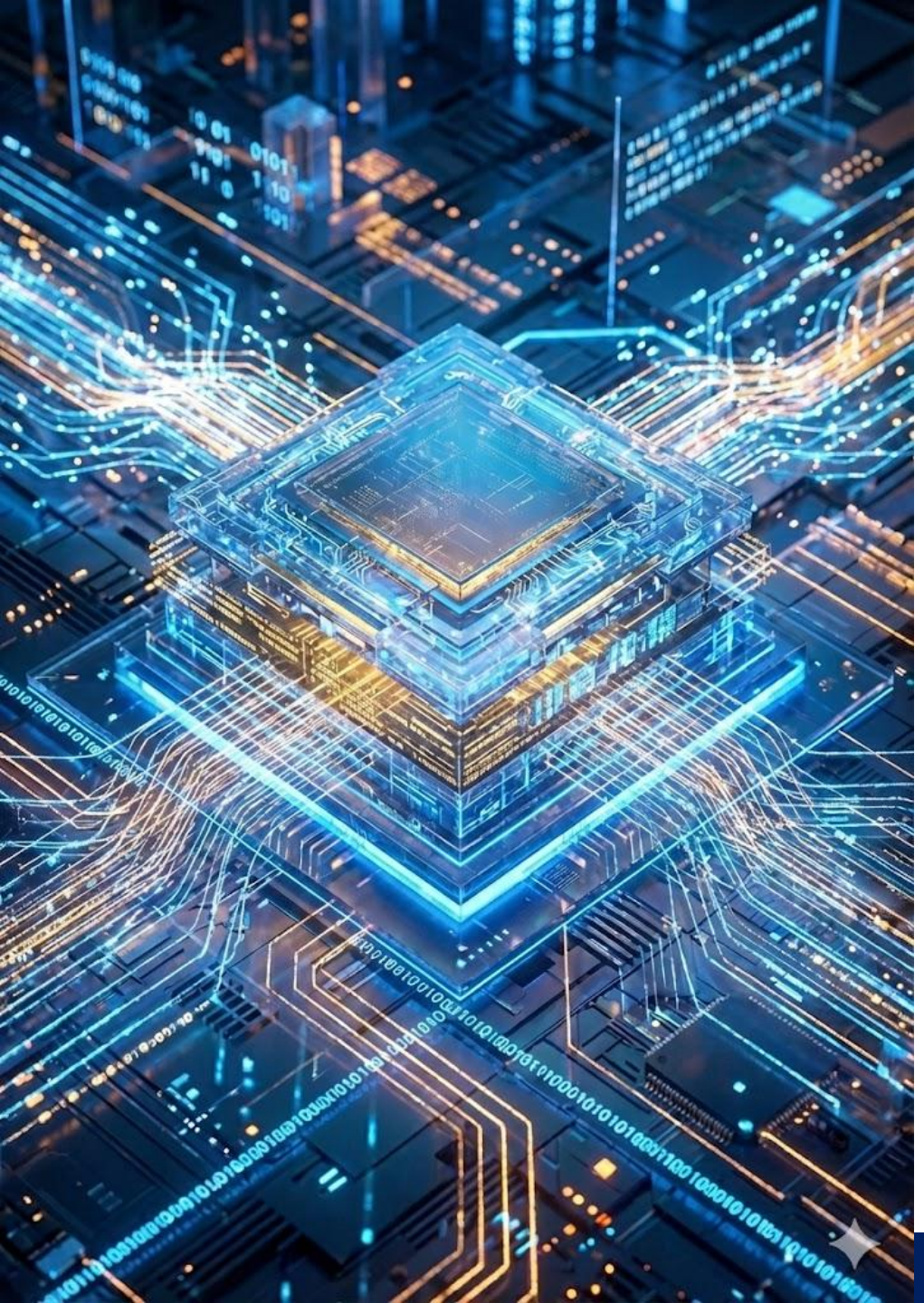
Corporate Governance

4 Independent directors, accounting for more than 44%
2 Female directors, accounting for more than 22%

The first Sustainability Report was issued in 2025 and will be published regularly on an annual basis.

Friendly Workplace

The company places great emphasis on gender equality and diversified development, with female employees and female managers each accounting for more than 30% of the workforce.



Feedback & Discussion

Thank you for listening.

For further information, please visit our website at:
https://www.aemc.com.tw/

Contact Investor Relations at:
ir@aemc.com.tw

Income Statement

NT$ million	1Q26	4Q25	1Q25	QOQ	YOY
Net Revenue / Net Sales	1,246	1,085	959	14.8%	29.8%
Gross Profit	566	477	375	18.6%	51.0%
Gross Margin	45.4%	44.0%	39.1%	3.3%	16.3%
Operating Expenses	229	224	183	1.8%	24.7%
Operating Profit	337	253	191	33.2%	76.1%
Operating Margin	27.1%	23.3%	19.9%	16.0%	35.7%
Non-operating Income and Expenses	73	72	59	1.5%	23.9%
Net Income Attributable to the Parent Company	340	262	208	29.8%	63.4%
EPS (NT$)	3.66	2.85	2.28	28.4%	60.5%

Balance Sheet

NT$ million	1Q26		4Q25		1Q25	
	Amount	%	Amount	%	Amount	%
Cash and Cash Equivalents	865	8.0%	938	8.6%	2,769	27.4%
Accounts Receivable	615	5.7%	536	4.9%	528	5.2%
Property, Plant and Equipment	3,881	35.7%	3,743	34.4%	2,942	29.1%
Total Assets	10,881	100.0%	10,469	96.2%	10,113	100.0%
Current Liabilities	1,679	15.4%	967	8.9%	1,391	13.8%
Long-term Borrowings	-	0.0%	-	0.0%	225	2.2%
Total Liabilities	1,931	17.7%	1,217	11.2%	1,758	17.4%
Total Shareholders' Equity	8,942	82.2%	9,252	85.0%	8,355	82.6%
Key Financial Ratios						
Current Ratio	332%		638%		463%	
Debt Ratio	18%		12%		17%	
Net Asset Value Per Share(NT$)	96.42		99.77		90.09	

Cash Flow Statement

NT$ million	1Q26	4Q25	3Q25
Beginning Cash Balance	965	1,778	2,569
Cash Flows from Operating Activities	219	215	158
Depreciation and Amortization Expenses	77	76	224
Capital Expenditures	(192)	(698)	(124)
Long-term Borrowings	0	0	(974)
Ending Cash Balance	893	965	1,778
Free Cash Flow	27	(483)	34

Note: Free Cash Flow = Cash Flows from Operating Activities – Capital Expenditures

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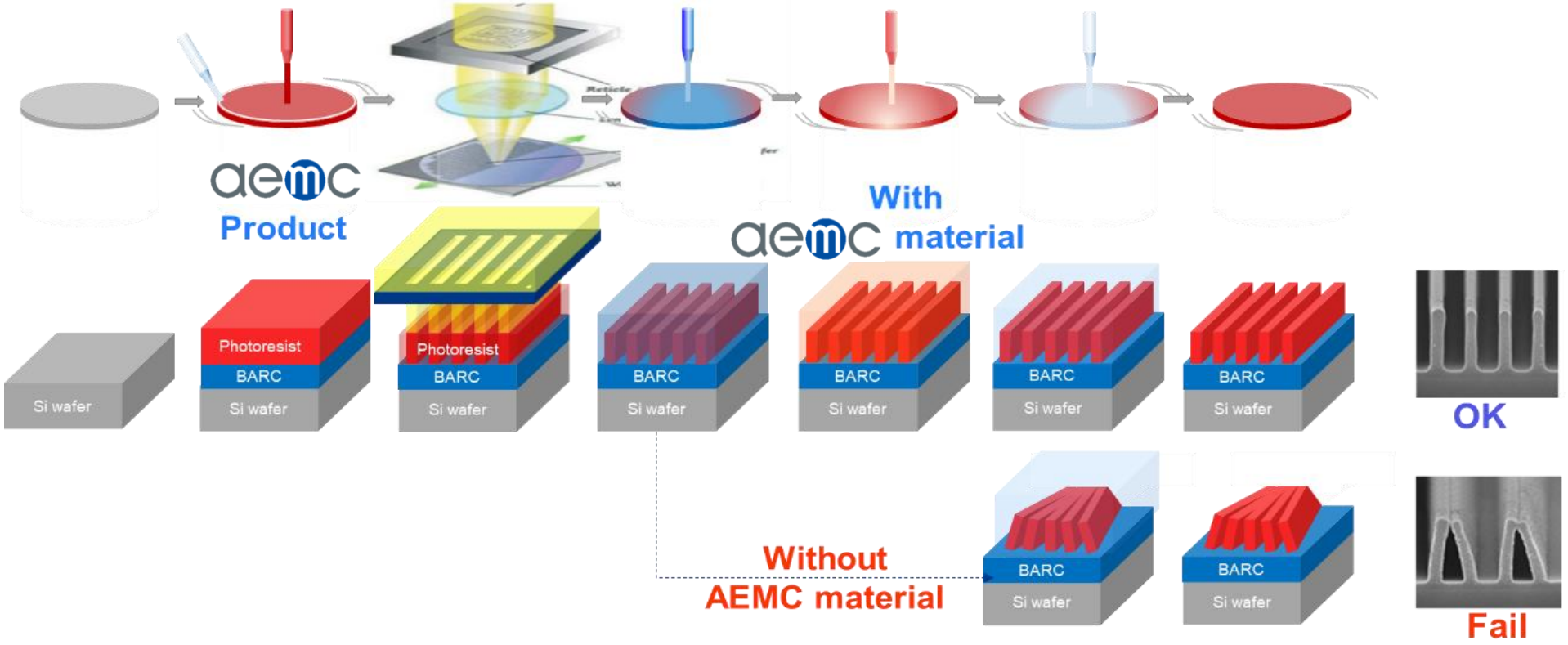
Lithography Materials for Advanced Semiconductor Processes

Products

- BARC
- EBR
- Rinse Material
- Cleaner (Pipeline and Equipment)



Key Material for Advanced Semiconductor Processes : Rinse

Benefits

√ Straightforward process

√ Pattern collapse mitigation

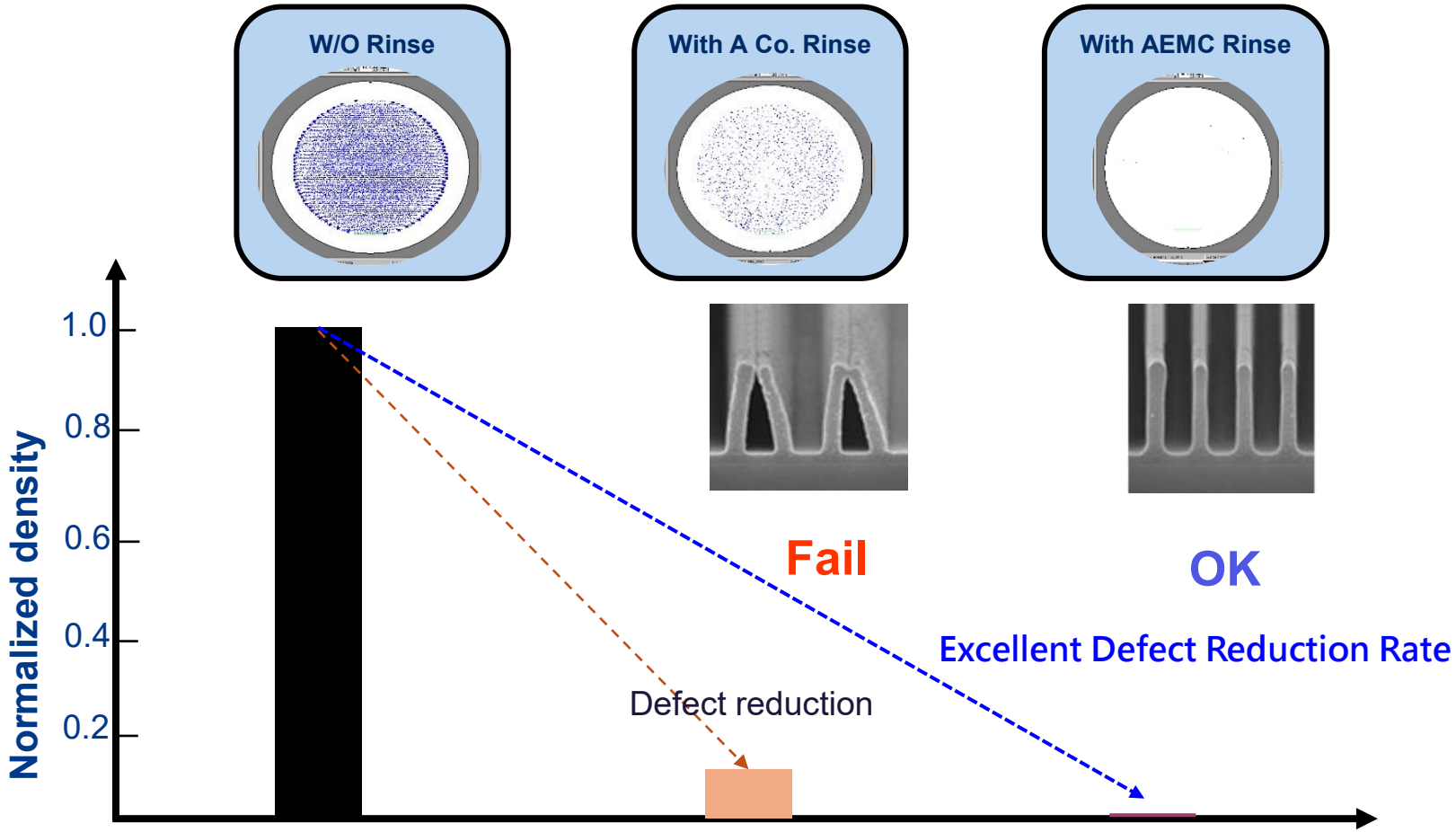
√ Defect reduction

Infusing Professional Resources to Enhance Supplier's R&D Capabilities

Lithography is a critical process in semiconductor manufacturing and is one of the core technologies that ensures chip quality and stability. Due to the high threshold for material research and production technology, the Lithography process has traditionally relied on imported materials. In 2019, in order to enhance the research and development capabilities and production efficiency of the domestic supply chain, TSMC's Material Supply Chain Management (MSCM) collaborated extensively with the Nano Patterning Technology Division (NPTD) to launch the 'Supplier Raw Material Technology Guidance Program'. Offering expert guidance on the seven major aspects of Lithography process materials, including technology development, quality assurance analysis, data calibration, sample verification, factory configuration, tank optimization, and production expansion planning. The program has not only effectively reduced the supplier's line setup and product verification time by 50%, but its material quality also surpasses TSMC's process standards, further improving yield rates and strengthening the competitiveness of the supplier in all aspects. This initiative has laid a solid foundation for the development of the domestic Lithography process material supply chain.

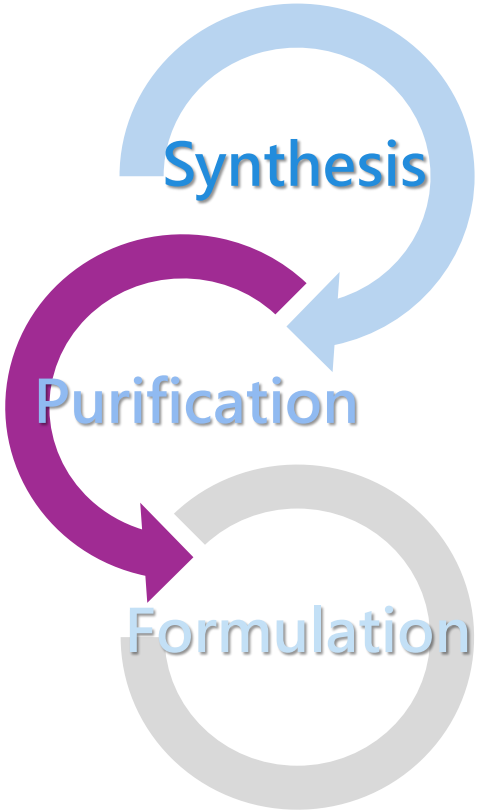
Source: Foundry Customers' ESG Website
https://esg.tsmc.com/zh-Hant/articles/74

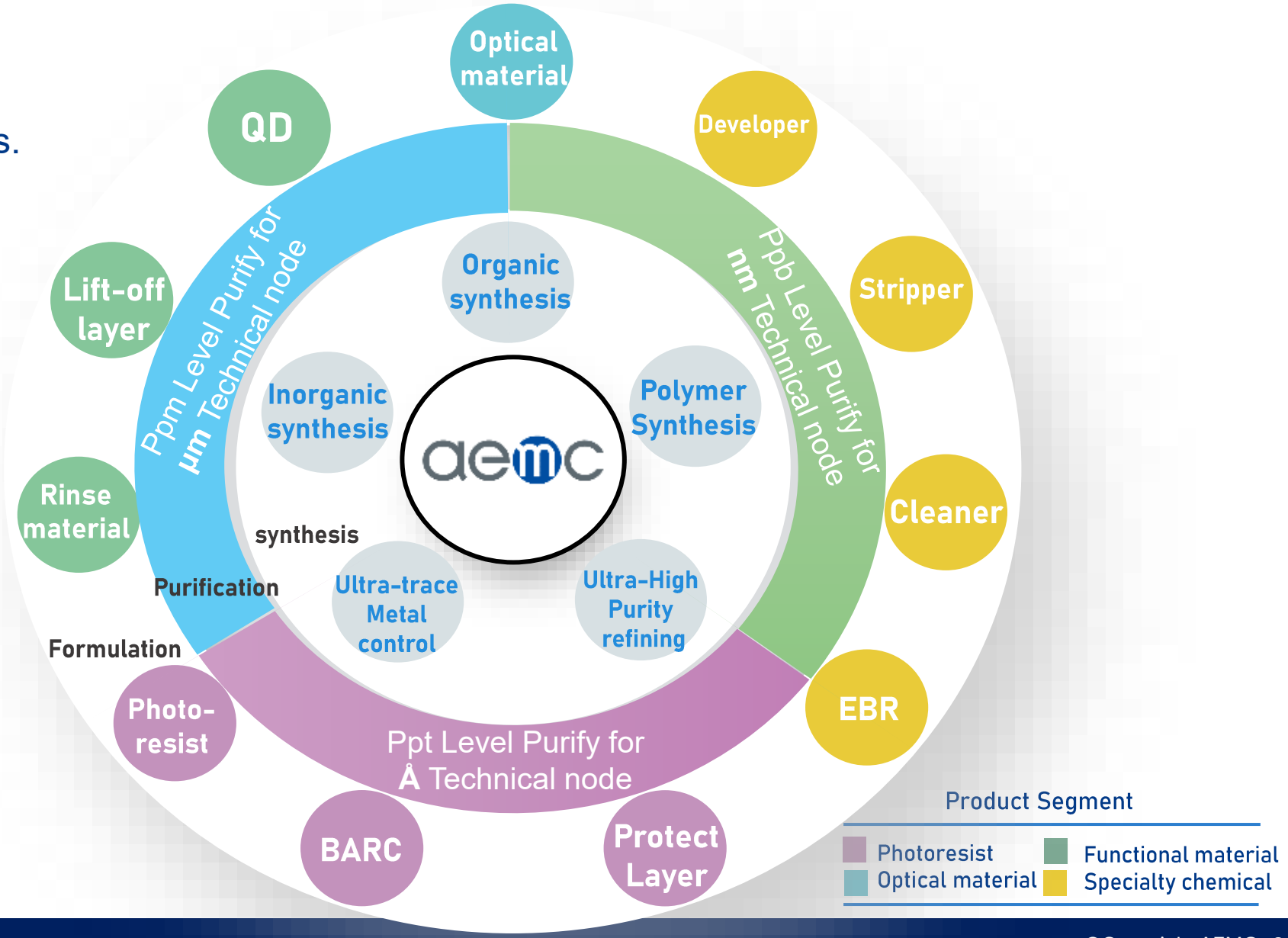
Defect Comparison:
The performance of AEMC's Rinse materials ranks No. 1 in the world.



Adv.1. Integrating Upstream From Formulation Technology

20 Years of Materials and
>1,000 Formulations Databases.





Adv 2. Establishing the Strategic Alliance for TW Material Supply Chain

Existing materials

Mainly relying on external purchases

Monomer/Precursor Synthesis

Self-synthesis or outsourcing(CDMO)

Domestic Universities and Research Institutions

Standard product

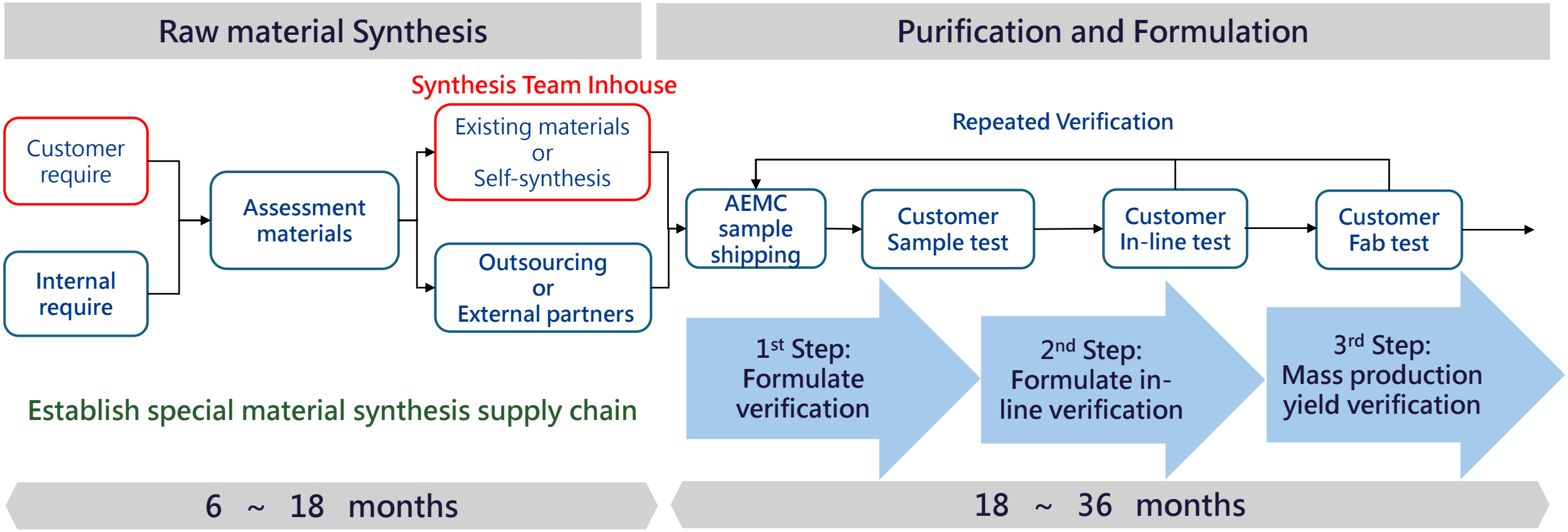
- Display： TFT-LCD

Customized

- Semiconductor：Advance Litho-process/Advance package process
- Semiconductor：Optical device
- Display：Micro LED

Adv.3. Fast Response Time and High Learning Curve

Higher response speed / Sample delivery frequency
Customized development



Adv.4. Excellent Quality Control Self Designed Manufacturing Technology

Excellent Quality Control

✓ **Quality Control Equipment and Systems:**

1. Building Equipment of the Same Level as Customers
2. Ultra-Trace Impurity Control to Meet the Requirements of Advanced Semiconductor Processes: Evolving from ppb (10^{-9}) to ppt (10^{-12}) levels
3. Intelligent Quality Monitoring System: Automated Product Inspection and Integrated Quality Data Analysis

Self Designed Manufacturing Technology

	Sample Shipping	Trial Production	Mass Production
Product			
In-house Production Line	R&D Lab	Mini line	High Volume Manufacturing

Note: Peer Products Comparison

Mass production V
Under verification O

Litho Process Materials		aemc	B*	M*	J*	S*	F*	T*	S*	N*	D*
		TW	DE	DE	JP	JP	JP	JP	JP	JP	US
Photoresist	CIS	V					V				
	G/I-line	V		V	V	V	V	V	V		
	KrF	O		V	V	V	V	V	V		V
	ArF	O		V	V	V	V	V	V		V
	EUV				V	V		V	V		
Peripheral Materials	BARC	V								V	V
	Rinse	V		V							
	Cleaner	V	V								
	Developer	V						V			
	EBR	V	V	V	V			V			
	Insulation layer materials	O								V	

Note: Compiled by Mega Securities, based on the company's official website and public information.
The materials above focus on the front-end process of semiconductors.

